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Photocouplers GaAs Infrared LED & Photo Triac

TLP3073, TLP3073F

1. Applications

- Solid-State Relays
- Triac Drivers
- Home Electric Appliances
- Office Equipment

2. General

The TLP3073 consists of a non zero crossing photo triac, optically coupled to a gallium arsenide infrared emitting diode. The TLP3073 is housed in the DIP6 package and guarantees insulation thickness of 0.4 mm (min). Therefore, the TLP3073 meets the reinforced insulation class requirements of international safety standards.

3. Features

- (1) Halogen-free

For details, see "Devices in Halogen-Free Resin Packages" at the end of this datasheet.

- (2) Peak off-state voltage: 800 V (min)
 (3) Non zero crossing functionary (NZC)
 (4) Trigger LED current: 5 mA (max)
 (5) On-state current: 100 mA (max)
 (6) Isolation voltage: 5000 Vrms (min)
 (7) Safety standards

UL-approved: UL1577, File No.E67349

cUL-approved: CSA Component Acceptance Service No.5A File No.E67349

VDE-approved: EN60747-5-5, EN60065 or EN60950-1 (**Note 1**)

CQC-approved: GB4943.1, GB8898 Japan Factory

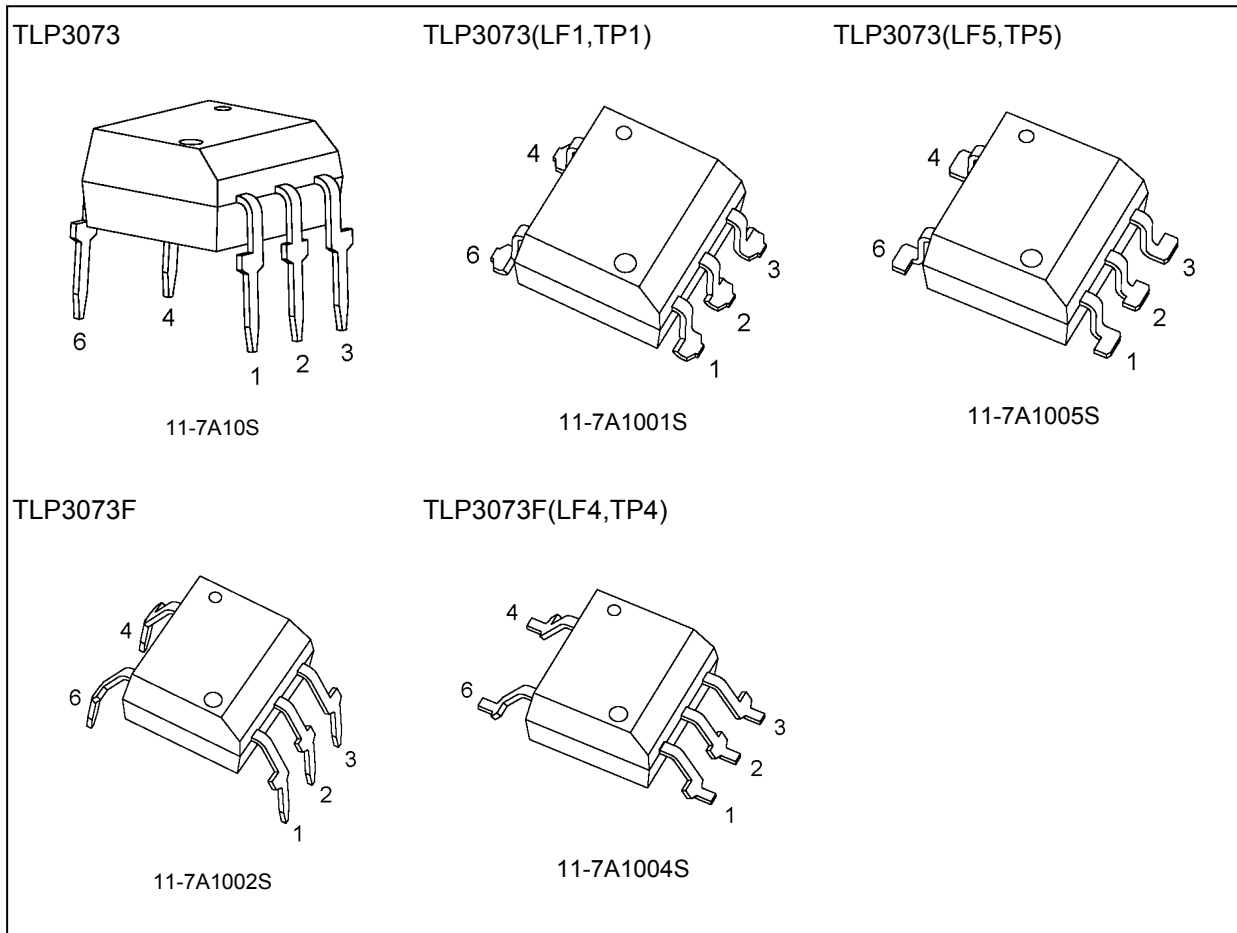
Note 1: When a VDE approved type is needed, please designate the **Option (D4)**.

Table 3.1 Mechanical Parameters

Characteristics	7.62 mm pitch TLP3073	10.16 mm pitch TLP3073F	Unit
Creepage distances	7.0 (min)	8.0 (min)	mm
Clearance distances	7.0 (min)	8.0 (min)	
Internal isolation thickness	0.4 (min)	0.4 (min)	

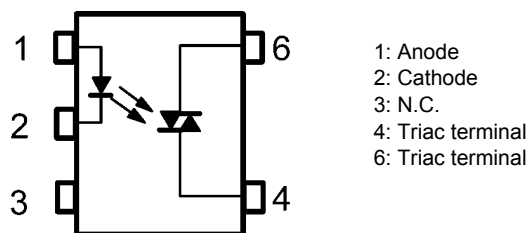
Start of commercial production
2015-08

4. Packaging (Note)



Note: Through-hole type: TLP3073, TLP3073F
 Lead forming option: (LF1), (LF4), (LF5)
 Taping option: (TP1), (TP4), (TP5)

5. Pin Assignment



6. Product Naming Conventions

Type of package used for shipment is denoted by a symbol suffix after a part number. The method of classification is as below.

Example) TLP3073(TP1,F

Part number: TLP3073

Tape type: TP1 (**Note 1**)

[[G]]/RoHS COMPATIBLE: F (**Note 2**)

Note 1: At the part of tape type, below options are used including lead forming type.

TLP3073: LF1, TP1, LF5, TP5

TLP3073F: LF4, TP4

Note 2: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

7. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25\text{ °C}$)

	Characteristics	Symbol	Note	Rating	Unit
LED	Input forward current	I_F		50	mA
	Input forward current derating ($T_a \geq 53\text{ °C}$)	$\Delta I_F/\Delta T_a$		-0.7	mA/°C
	Input forward current (pulsed)	I_{FP}	(Note 1)	1	A
	Input reverse voltage	V_R		5	V
	Input power dissipation	P_D		100	mW
	Input power dissipation derating ($T_a \geq 25\text{ °C}$)	$\Delta P_D/\Delta T_a$		-1.0	mW/°C
	Junction temperature	T_j		125	°C
Detector	Off-state output terminal voltage	V_{DRM}		800	V
	R.M.S. on-state current	$I_{T(RMS)}$	($T_a = 25\text{ °C}$)	100	mA
			($T_a = 70\text{ °C}$)	50	mA
	R.M.S. on-state current derating ($T_a \geq 25\text{ °C}$)	$\Delta I_{T(RMS)}/\Delta T_a$		-1.1	mA/°C
	ON-state current (pulsed)	I_{ONP}	(Note 2)	2	A
	Peak non-repetitive surge current	I_{TSM}	(Note 3)	1.2	A
	Output power dissipation	P_O		300	mW
	Output power dissipation derating ($T_a \geq 25\text{ °C}$)	$\Delta P_O/\Delta T_a$		-4.0	mW/°C
	Junction temperature	T_j		125	°C
Common	Total power dissipation	P_T		400	mW
	Total power dissipation derating ($T_a \geq 25\text{ °C}$)	$\Delta P_T/\Delta T_a$		-4.4	mW/°C
	Operating temperature	T_{opr}		-40 to 100	°C
	Storage temperature	T_{stg}		-55 to 125	
	Lead soldering temperature (10 s)	T_{sol}		260	
	Isolation voltage AC, 60 s, R.H. $\leq 60\%$	BV_S	(Note 4)	5000	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Pulse width (PW) $\leq 100\text{ }\mu\text{s}$, 100 pps

Note 2: Pulse width (PW) $\leq 100\text{ }\mu\text{s}$, 120 pps

Note 3: Pulse width (PW) $\leq 10\text{ ms}$

Note 4: This device is considered as a two-terminal device: Pins 1, 2 and 3 are shorted together, and pins 4 and 6 are shorted together.

8. Recommended Operating Conditions (Note)

Characteristics	Symbol	Note	Min	Typ.	Max	Unit
AC mains voltage	V_{AC}	(Note 1)	—	—	480	V
Input forward current	I_F		7.5	10	20	mA
ON-state current (pulsed)	I_{ONP}		—	—	1	A
Operating temperature	T_{opr}		-25	—	85	°C

Note: The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this data sheet should also be considered.

Note 1: AC use only.

9. Electrical Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

	Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
LED	Input forward voltage	V_F		$I_F = 10\text{ mA}$	1.0	1.15	1.3	V
	Input reverse current	I_R		$V_R = 5\text{ V}$	—	—	10	μA
	Input capacitance	C_t		$V = 0\text{ V}, f = 1\text{ MHz}$	—	30	—	pF
Detector	Peak off-state current	I_{DRM}		$V_{\text{DRM}} = 800\text{ V}$	—	10	1000	nA
	Peak on-state voltage	V_{TM}		$I_{\text{TM}} = 100\text{ mA}$	—	1.7	3.0	V
	Holding current	I_H		—	—	1.0	—	mA
	Critical rate of rise of off-state voltage	dv/dt		$V_{\text{in}} = 240\text{ V}, T_a = 25\text{ }^\circ\text{C}$ See Fig. 9.1	—	2000	—	V/ μs
	Critical rate of rise of commutating voltage (dv/dt)	dv/dt(c)		$V_{\text{in}} = 60\text{ Vrms}, I_T = 15\text{ mA}$ See Fig. 9.1	—	0.2	—	

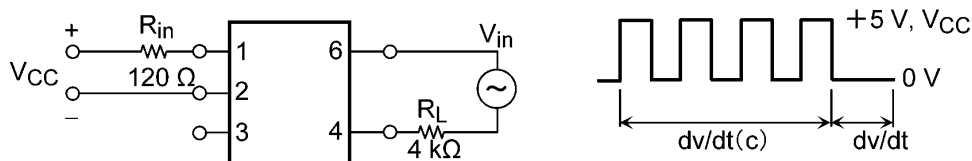


Fig. 9.1 dv/dt Test Circuit and Waveform

10. Coupled Electrical Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Trigger LED current	I_{FT}		$V_T = 6\text{ V}$	—	—	5	mA

11. Isolation Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Total capacitance (input to output)	C_S	(Note 1)	$V_S = 0\text{ V}, f = 1\text{ MHz}$	—	0.8	—	pF
Isolation resistance	R_S	(Note 1)	$V_S = 500\text{ V}, \text{R.H.} \leq 60\%$	1×10^{12}	10^{14}	—	Ω
Isolation voltage	BV_S	(Note 1)	AC, 60 s	5000	—	—	Vrms
			AC, 1 s in oil	—	10000	—	
			DC, 60 s in oil	—	10000	—	Vdc

Note 1: This device is considered as a two-terminal device: Pins 1, 2 and 3 are shorted together, and pins 4 and 6 are shorted together.

12. Characteristics Curves (Note)

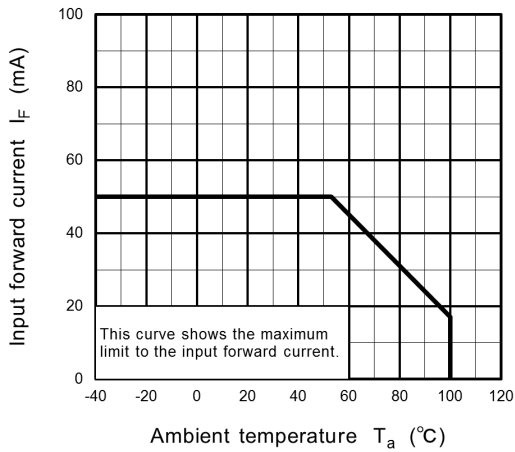


Fig. 12.1 $I_F - T_a$

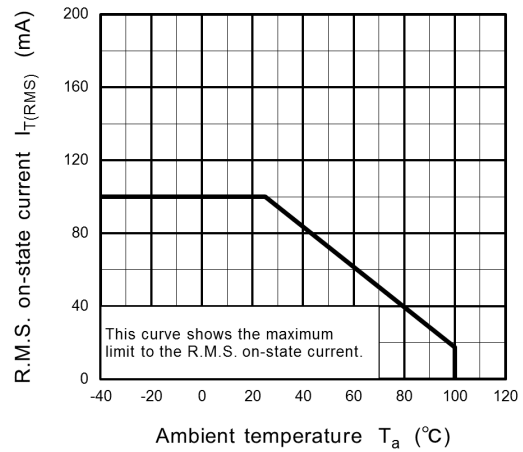


Fig. 12.2 $I_{T(RMS)} - T_a$

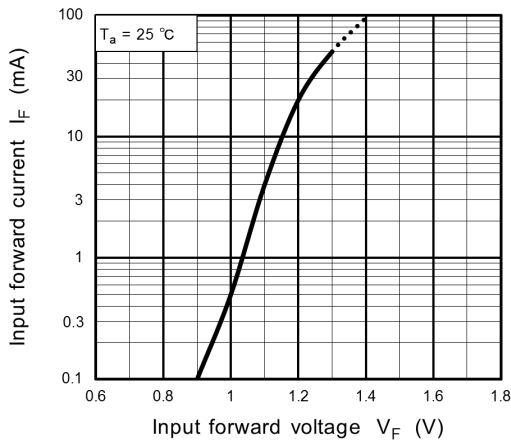


Fig. 12.3 $I_F - V_F$

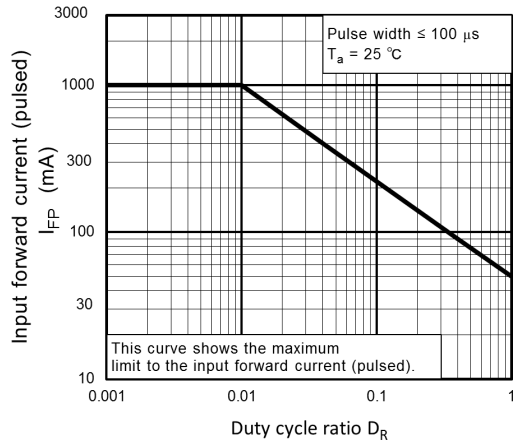


Fig. 12.4 $I_{FP} - D_R$

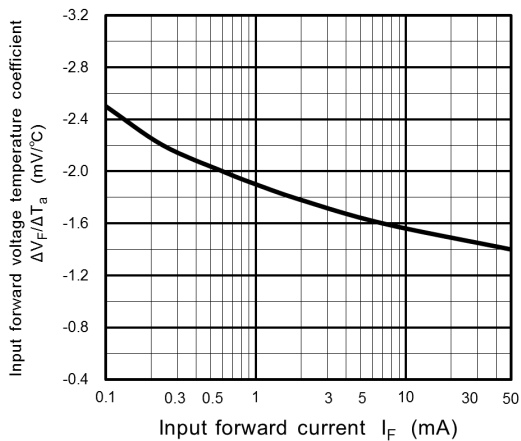


Fig. 12.5 $\Delta V_F/\Delta T_a - I_F$

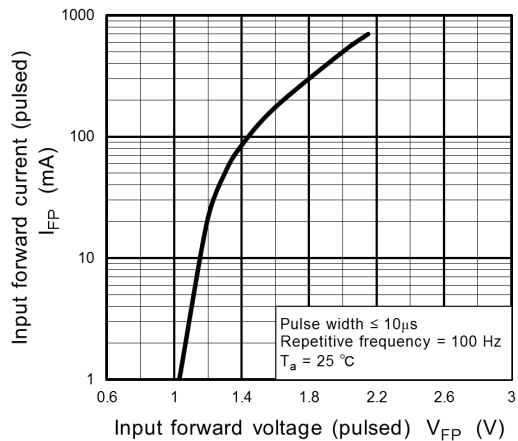


Fig. 12.6 $I_{FP} - V_{FP}$

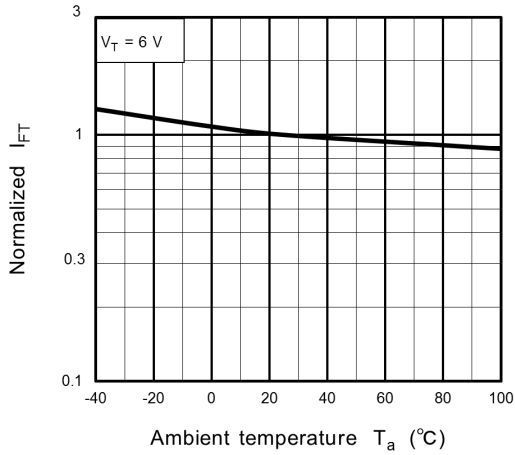


Fig. 12.7 Normalized I_{FT} - T_a

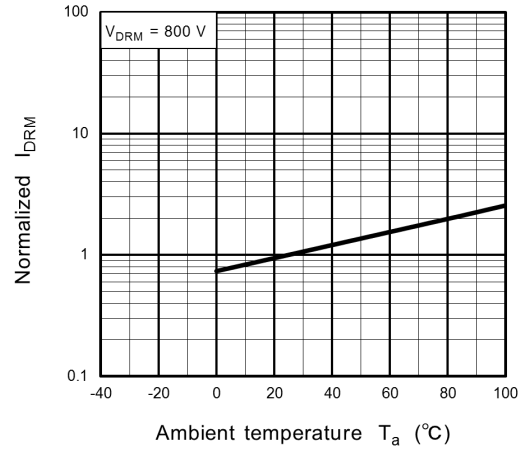


Fig. 12.8 Normalized I_{DRM} - T_a

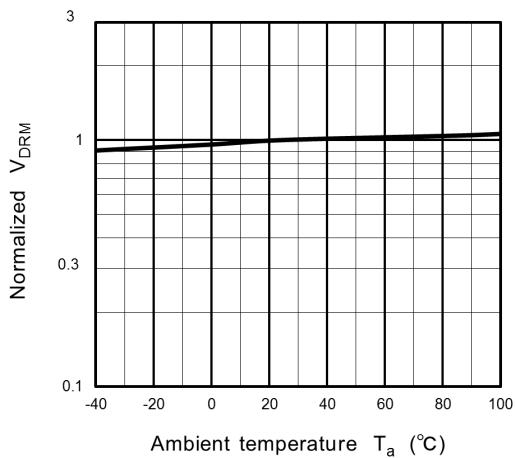


Fig. 12.9 Normalized V_{DRM} - T_a

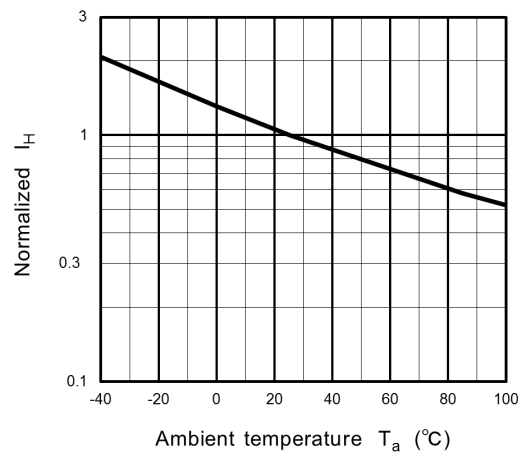


Fig. 12.10 Normalized I_H - T_a

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

13. Soldering and Storage

13.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

- When using soldering reflow.

The soldering temperature profile is based on the package surface temperature.

(See the figure shown below, which is based on the package surface temperature.)

Reflow soldering must be performed once or twice.

The mounting should be completed with the interval from the first to the last mountings being 2 weeks.

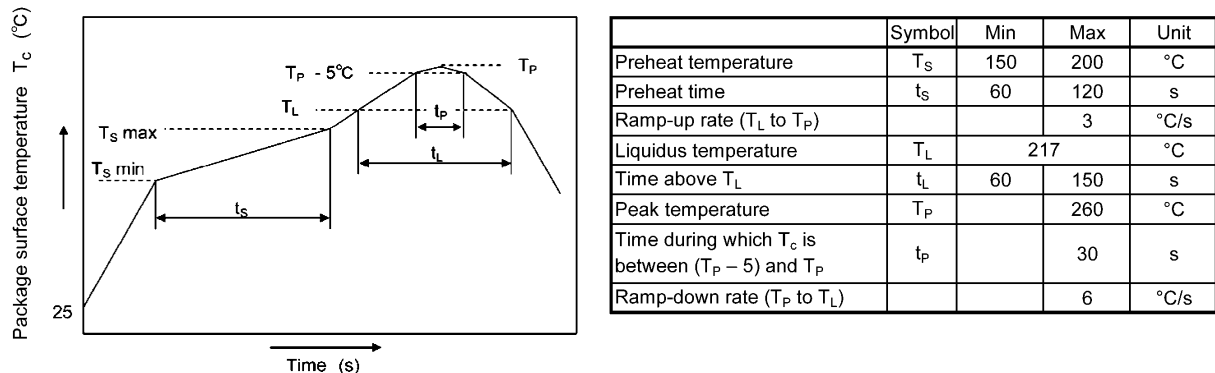


Fig. 13.1.1 An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

- When using soldering flow
Preheat the device at a temperature of 150 °C (package surface temperature) for 60 to 120 seconds.
Mounting condition of 260 °C within 10 seconds is recommended.
Flow soldering must be performed once.
- When using soldering Iron
Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C
Heating by soldering iron must be done only once per lead.

13.2. Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45 % to 75 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

14. Land Pattern Dimensions (for reference only)

(Unit: mm)

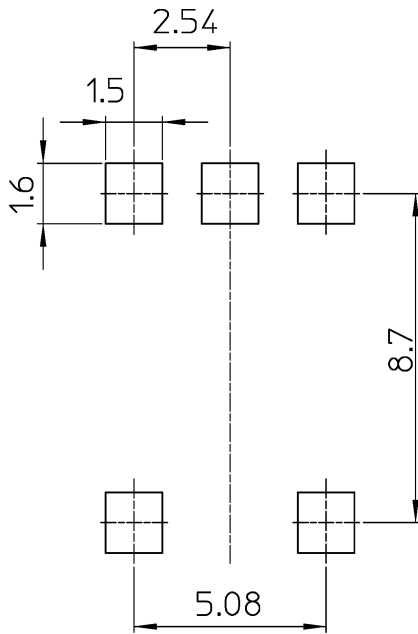


Fig. 14.1 TLP3073
Lead forming and taping option
(LF1), (TP1), (LF5), (TP5)

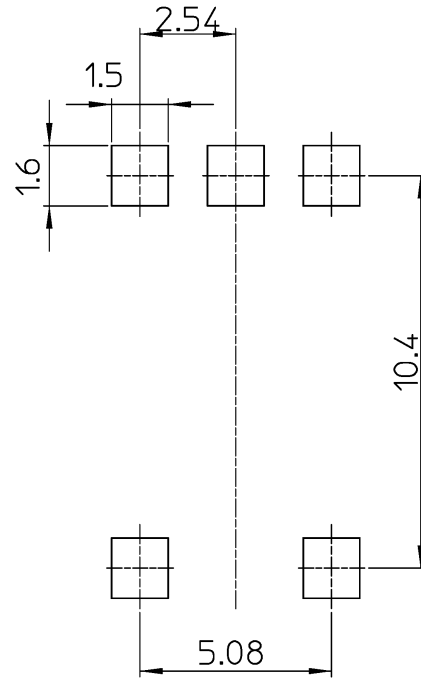


Fig. 14.2 TLP3073F
Lead forming and taping option
(LF4), (TP4)

15. EN60747-5-5 Option (D4) Specification

- Part number: TLP3073 (**Note 1**)
- The following part naming conventions are used for the devices that have been qualified according to option (D4) of EN60747.
 Example: TLP3073(D4,TP1,F)
 D4: EN60747 option
 TP1: Tape type
 F: [[G]]/RoHS COMPATIBLE (**Note 2**)

Note 1: Use TOSHIBA standard type number for safety standard application.
 e.g., TLP3073(D4,TP1,F → TLP3073

Note 2: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Description		Symbol	Rating	Unit
Application classification for rated mains voltage ≤ 300 Vrms for rated mains voltage ≤ 600 Vrms			I-IV I-III	—
Climatic classification			40 / 100 / 21	—
Pollution degree			2	—
Maximum operating insulation voltage	TLPxxxx type	V_{IORM}	890	V_{peak}
	TLPxxxxF type		1140	
Input to output test voltage, Method A $V_{pr} = 1.6 \times V_{IORM}$, type and sample test $t_p = 10$ s, partial discharge < 5 pC	TLPxxxx type	V_{pr}	1424	V_{peak}
	TLPxxxxF type		1824	
Input to output test voltage, Method B $V_{pr} = 1.875 \times V_{IORM}$, 100 % production test $t_p = 1$ s, partial discharge < 5 pC	TLPxxxx type	V_{pr}	1670	V_{peak}
	TLPxxxxF type		2140	
Highest permissible overvoltage (transient overvoltage, $t_{pr} = 60$ s)		V_{TR}	8000	V_{peak}
Safety limiting values (max. permissible ratings in case of fault, also refer to thermal derating curve) current (input current I_F , $P_{SO} = 0$) power (output or total power dissipation) temperature		I_{Si} P_{SO} T_S	400 700 150	mA mW °C
Insulation resistance	$V_{IO} = 500$ V, $T_a = 25$ °C $V_{IO} = 500$ V, $T_a = 100$ °C $V_{IO} = 500$ V, $T_a = T_s$	R_{Si}	$\geq 10^{12}$ $\geq 10^{11}$ $\geq 10^9$	Ω

Fig. 15.1 EN60747 Insulation Characteristics

Table Insulation Related Specifications (Note)

Insulation Related Parameters	Symbol	TLP3073	TLP3073F
Minimum creepage distance	Cr	7.0 mm	8.0 mm
Minimum clearance	Cl	7.0 mm	8.0 mm
Minimum insulation thickness	ti	0.4 mm	0.4 mm
Comparative tracking index	CTI	175	175

Note: If a printed circuit is incorporated, the creepage distance and clearance may be reduced below this value. (e. g., at a standard distance between soldering eye centers of 7.5 mm). If this is not permissible, the user shall take suitable measures.

Note: This photocoupler is suitable for **safe electrical isolation** only within the safety limit data. Maintenance of the safety data shall be ensured by means of protective circuits.



Fig. 15.2 Marking on packing for EN60747

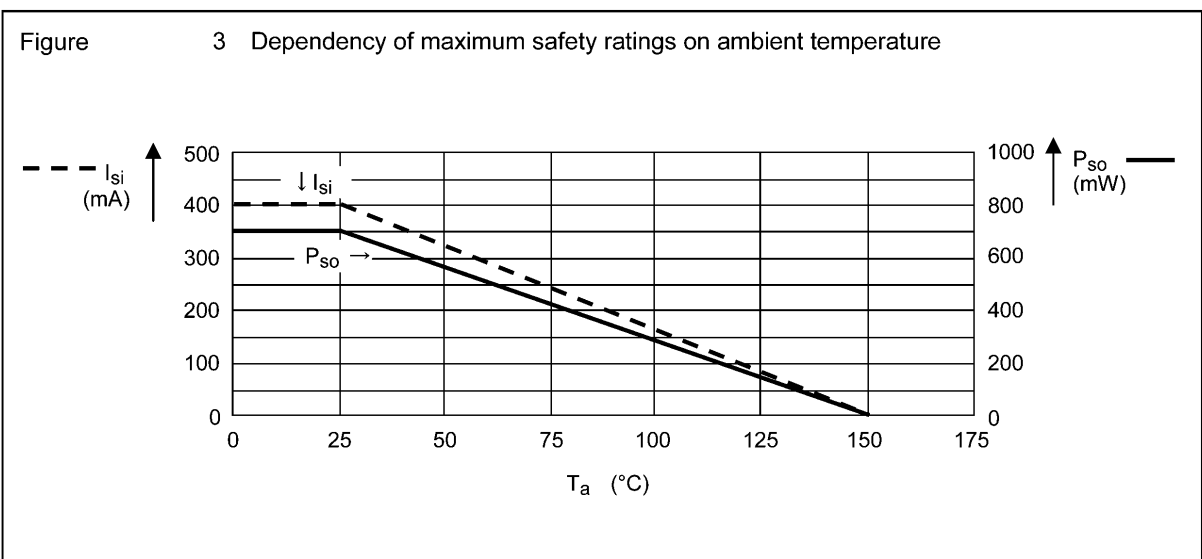
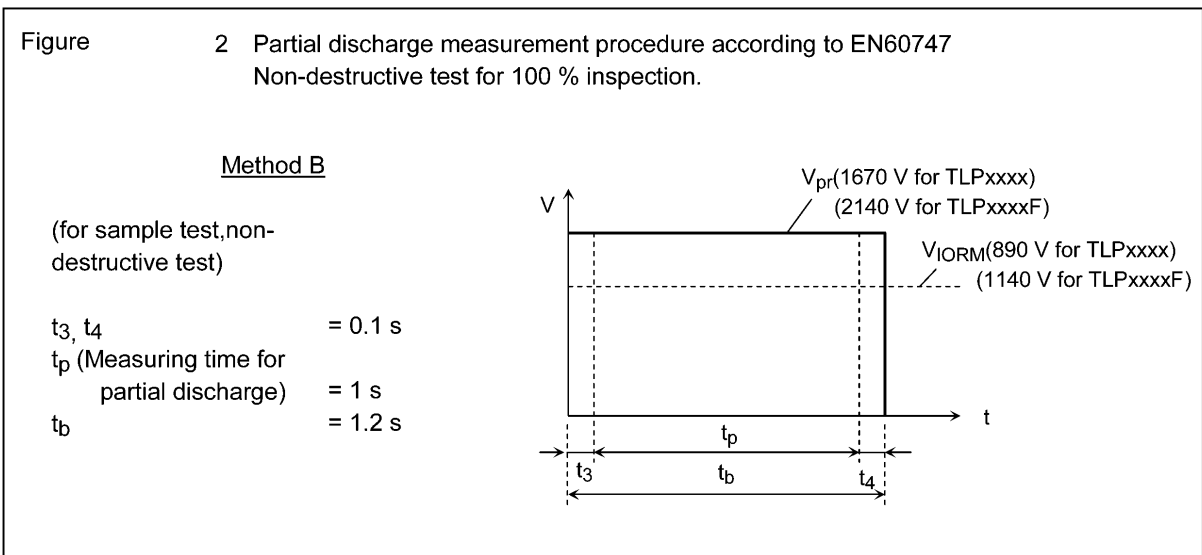
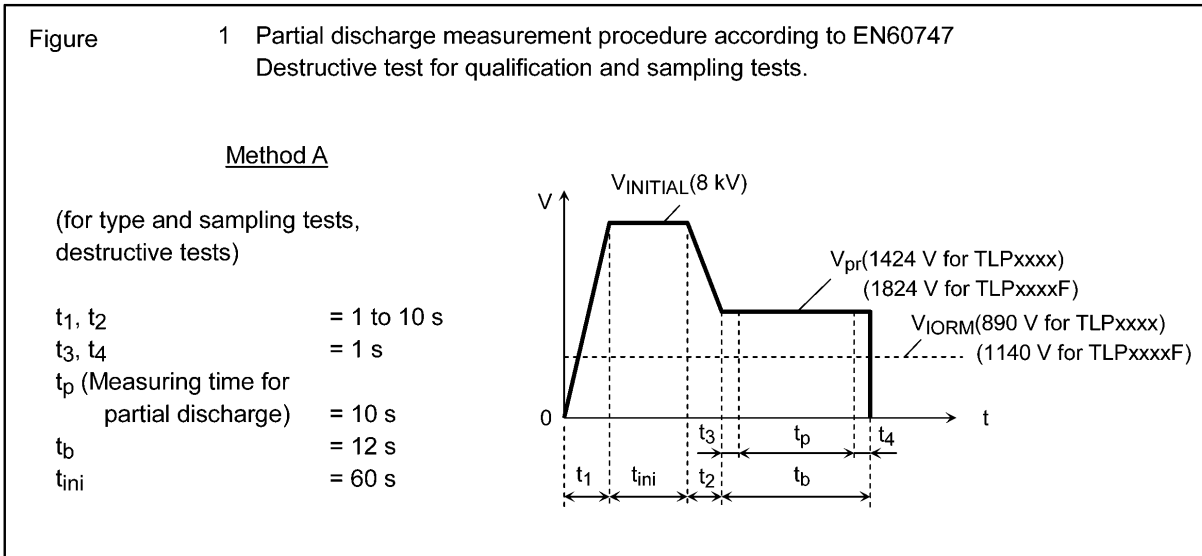


Fig. 15.3 Measurement Procedure

16. Ordering Information (Example of Item Name)

Item Name	Packaging (Note 1)	VDE Option	Packing (MOQ)
TLP3073(F	TH		Magazine (50 pcs)
TLP3073(LF1,F	LF1		Magazine (50 pcs)
TLP3073(LF5,F	LF5		Magazine (50 pcs)
TLP3073(TP1,F	LF1		Tape and reel (1500 pcs)
TLP3073(TP5,F	LF5		Tape and reel (1500 pcs)
TLP3073(D4,F	TH	EN60747-5-5	Magazine (50 pcs)
TLP3073(D4,LF1,F	LF1	EN60747-5-5	Magazine (50 pcs)
TLP3073(D4,LF5,F	LF5	EN60747-5-5	Magazine (50 pcs)
TLP3073(D4,TP1,F	LF1	EN60747-5-5	Tape and reel (1500 pcs)
TLP3073(D4,TP5,F	LF5	EN60747-5-5	Tape and reel (1500 pcs)
TLP3073F(F	TH, Wide forming		Magazine (50 pcs)
TLP3073F(LF4,F	LF4, Wide forming		Magazine (50 pcs)
TLP3073F(TP4,F	LF4, Wide forming		Tape and reel (1000 pcs)
TLP3073F(D4,F	TH, Wide forming	EN60747-5-5	Magazine (50 pcs)
TLP3073F(D4,LF4F	LF4, Wide forming	EN60747-5-5	Magazine (50 pcs)
TLP3073F(D4,TP4F	LF4, Wide forming	EN60747-5-5	Tape and reel (1000 pcs)

Note 1: TH: Through-hole, LF: Lead forming for surface mount

17. Devices in Halogen-Free Resin Packages

- This product is Halogen-Free

Toshiba Electronic Devices & Storage Corporation ("Toshiba") defines a "Halogen-Free resin semiconductor product" as a semiconductor product in which:

- (1) the encapsulating resins do not contain any of the following elements: bromine (Br), chlorine (Cl) and antimony (Sb), respectively, in an amount exceeding 0.09 weight percent, and do not contain chlorine and bromine in an aggregate amount exceeding 0.15 weight percent of the encapsulating resins, and/or
- (2) the resin portion(s) in printed circuit boards do not contain any of the following elements: bromine, chlorine and antimony, respectively, in an amount exceeding 0.09 weight percent, and do not contain chlorine and bromine in an aggregate amount exceeding 0.15 weight percent of the each resin portion(s) in printed circuit boards.

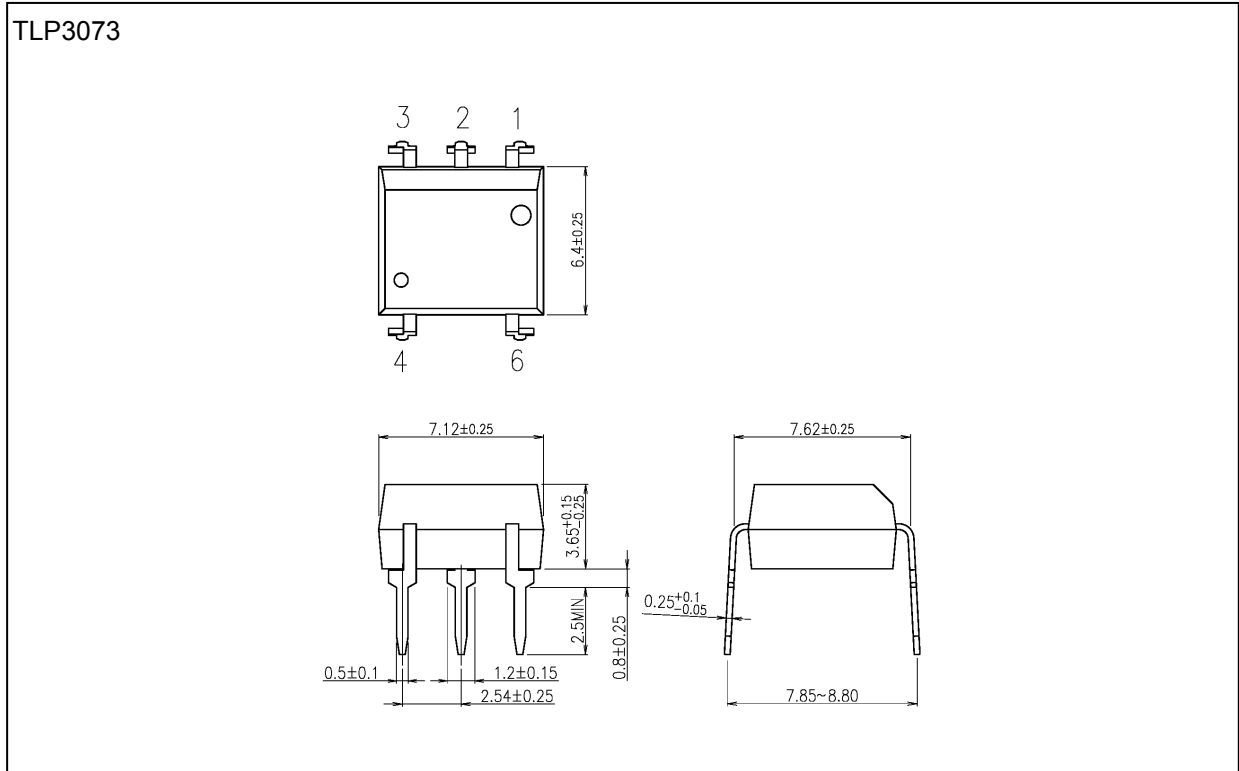
For avoidance of doubt, "Halogen-Free resin semiconductor product" does not mean, and Toshiba does not make any warranty of any kind, that said semiconductor product is entirely free of antimony or of any of the following elements of the halogen family: bromine, chlorine, iodine (I), fluorine (F) and astatine (At).

In addition, a Halogen-Free resin semiconductor product may contain antimony and/or any of the elements of the halogen family as mentioned in the above paragraph in one or more portion(s) of the semiconductor product other than the encapsulating resins and the resin portion(s) in printed circuit boards.

The information provided herein is accurate as of the date that it was provided, to the best of the knowledge and belief of the Toshiba Electronic Devices & Storage Corporation ("Toshiba"), Toshiba bases such knowledge and belief on information provided by third parties, and Toshiba makes no representation or warranty as to the accuracy of such third party information. Toshiba has taken and will continue to take, reasonable steps to provide accurate information to its customers, but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals.

Package Dimensions

Unit: mm

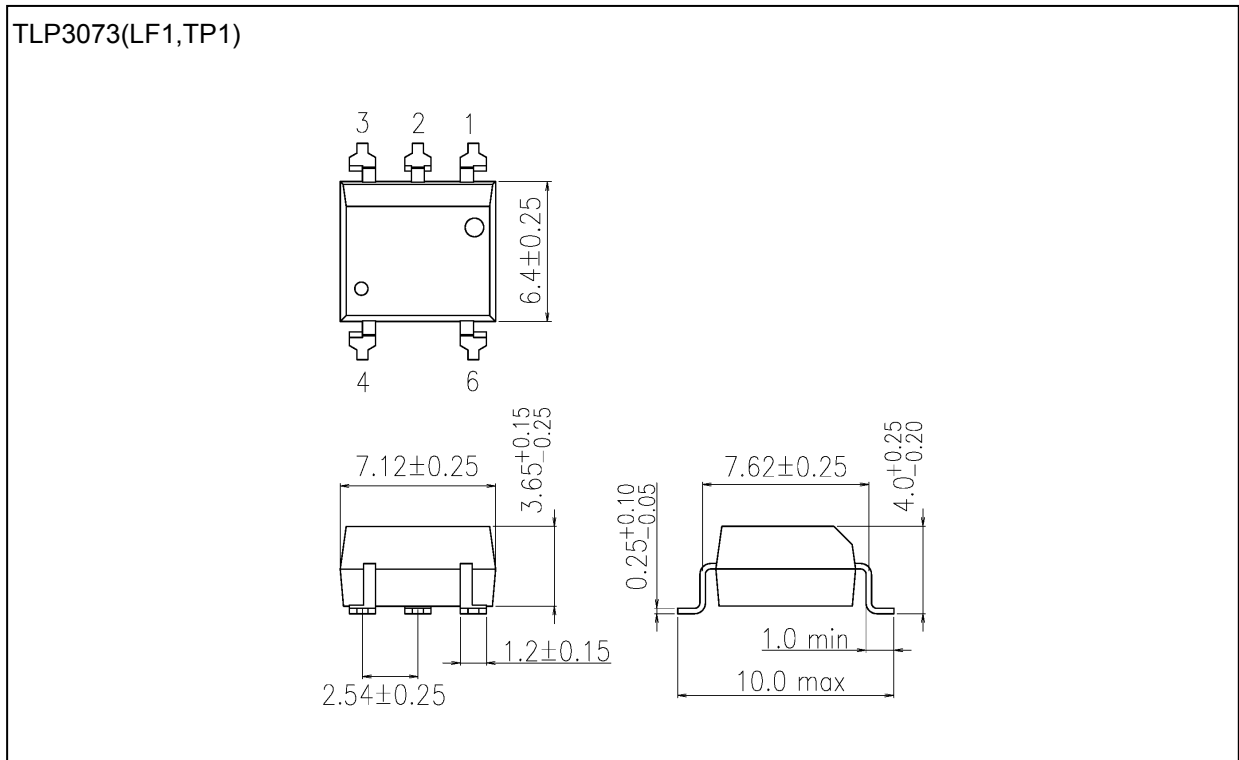


Weight: 0.40 g (typ.)

Package Name(s)
TOSHIBA: 11-7A10S

Package Dimensions

Unit: mm

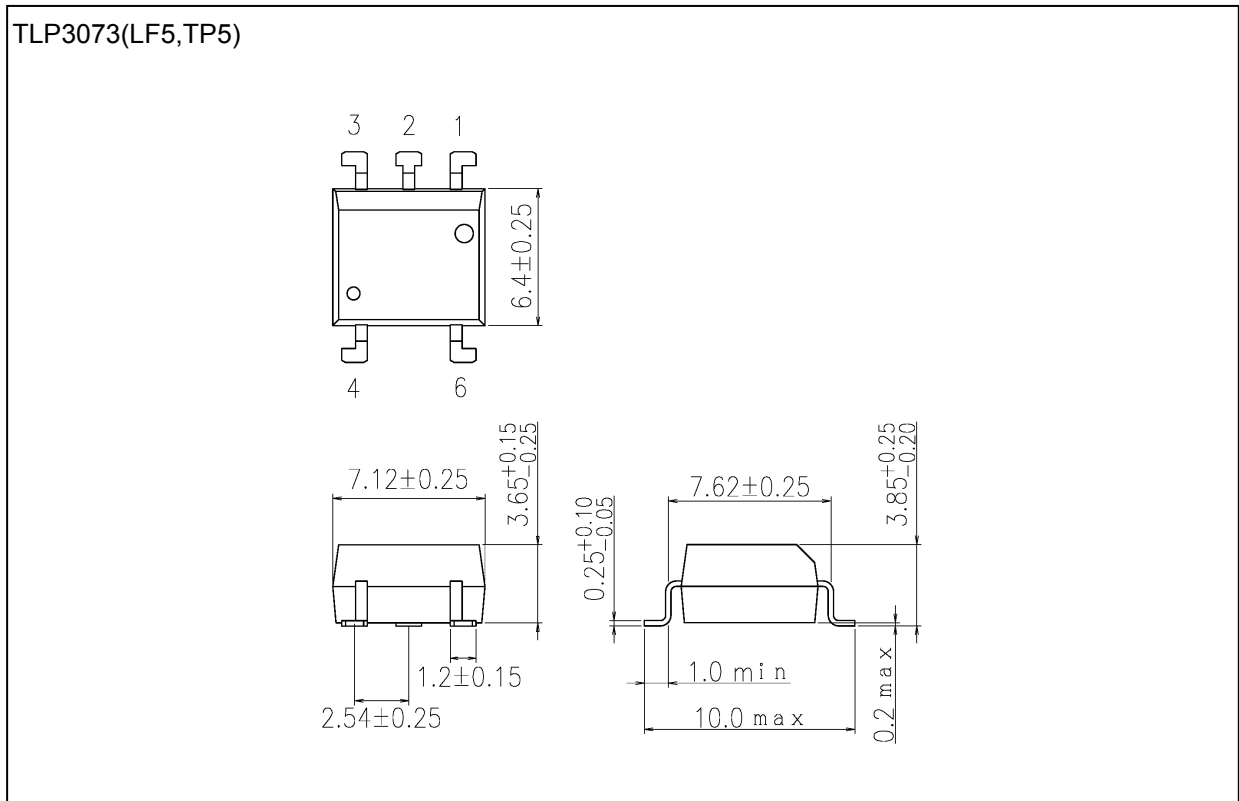


Weight: 0.39 g (typ.)

Package Name(s)
TOSHIBA: 11-7A1001S

Package Dimensions

Unit: mm

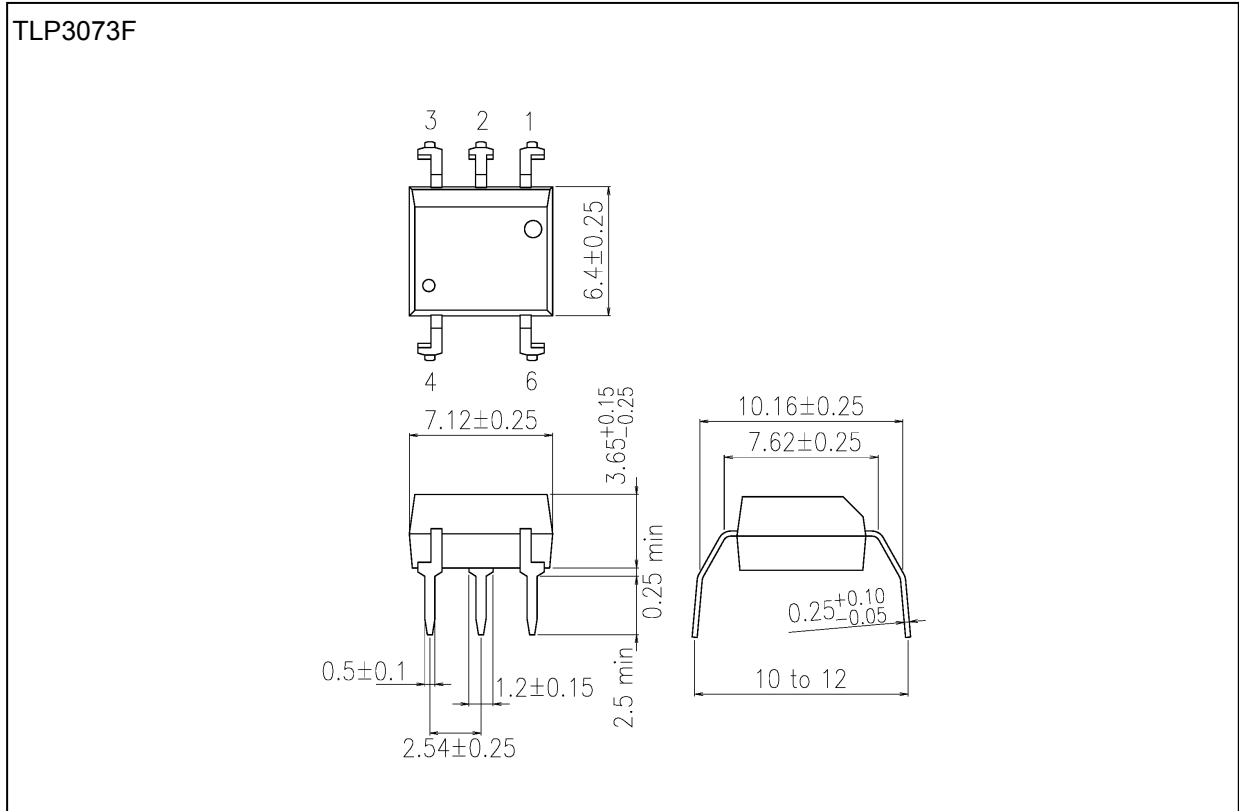


Weight: 0.39 g (typ.)

Package Name(s)
TOSHIBA: 11-7A1005S

Package Dimensions

Unit: mm

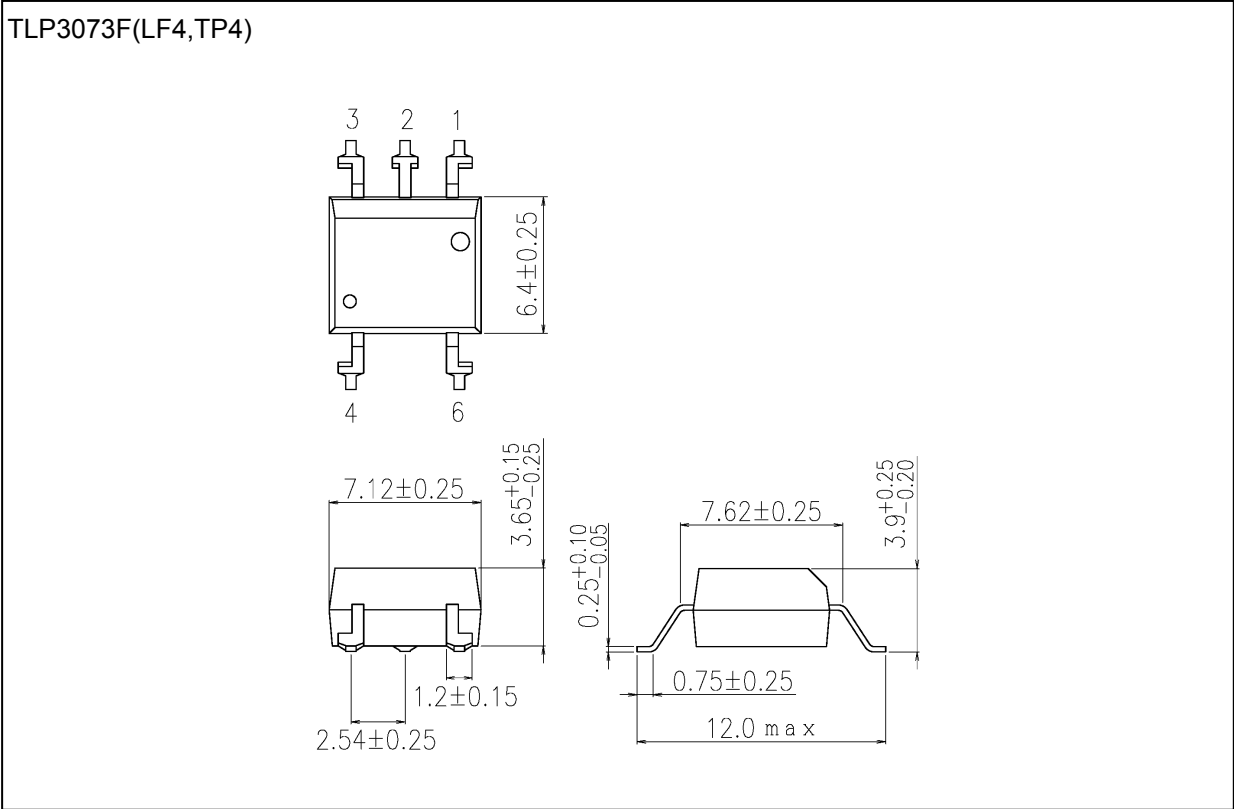


Weight: 0.40 g (typ.)

Package Name(s)
TOSHIBA: 11-7A1002S

Package Dimensions

Unit: mm



Weight: 0.39 g (typ.)

Package Name(s)
TOSHIBA: 11-7A1004S

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